NOTES:
1. Ø REPRESENTS A CRITICAL DIMENSION.
2. CONTACT POINTS ARE MEASURED IN UNCOMPRESSED STATE.
3. RECOMMENDED SCREW SIZE: M1.6
4. ELECTRICAL TEST: TESTED TO STANDARD
100% ISOLATION & CONTINUITY TESTS REQUIRED
100% HI-POT REQUIRED AT 3000V
MINIMUM PIN TO PIN ISOLATION TO BE 200 MEGA OHMS
5. PARTS TO BE PACKAGED IN TRAYS.
6. DIMENSION AFTER FINAL REFLOW IS 1.000 [0.394].
7. MAXIMUM BURR AFTER Dicing: 0.125 [0.05].
8. PARTS TO BE PROCESSED PER SAMTEC WORKMANSHIP GUIDELINES: NA-ZR-WI-3015-M.
9. PAD SIZE IS DEFINED BY SOLDERMASK OPENING; SOLDERMASK THICKNESS IS 0.0254±0.0127mm
10. TOTAL STACK HEIGHT OF MATERIAL LAYERS IS REPRESENTED IN CONTACT ARRAY AREA. AREAS OUTSIDE OF THE ARRAY HAVE THE FOIL LAYER REMOVED RESULTING IN THINNER PROFILE DIMENSION OUTSIDE OF ARRAY.

FIG. 1
ZA1-10-2-1.00-X-10 SHOWN (DUAL COMPRESSION) (SOME CENTER FEATURES REMOVED FOR CLARITY)

TABLE 1

<table>
<thead>
<tr>
<th>No OF POSITIONS (PER ROW)</th>
<th>&quot;A&quot;</th>
<th>&quot;B&quot;</th>
<th>&quot;C&quot;</th>
</tr>
</thead>
<tbody>
<tr>
<td>-30</td>
<td>38.30 [1.508]</td>
<td>36.300 [1.4291]</td>
<td>33.00 [1.296]</td>
</tr>
<tr>
<td>-40</td>
<td>48.30 [1.902]</td>
<td>46.300 [1.828]</td>
<td>43.00 [1.693]</td>
</tr>
</tbody>
</table>

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS.
TOLERANCES ARE:
DECIMALS: ANGLES: X.X: ±0.3 [0.01] X.XX: ±0.13 [0.005] X.XXX: ±0.053 [0.002]
MATERIAL:
CONTACT: BeCu
CORE: FR4
COVERLAY: POLYIMIDE

REVISION H
DESIGNED & DIMENSIONED IN MILLIMETERS (INCHES)

SOLDER COMPOSITION
LEAVE BLANK FOR -2 COMPRESSION
-1: LEAD (63% Sn/37% Pb)
-2: LEAD-FREE (96.5% Sn/3% Ag/.5% Cu)
ROW SPECIFICATION
-10: 10 ROWS
PLATING SPECIFICATION
-2: 6µ" MIN Au OVER 40-100µ" Ni
-5: 30µ" MIN Au OVER 40-100µ" Ni
* NOT RELEASED
** ONLY AVAILABLE IN -10 & -20 POSITIONS

DEFINITIONS:
-0: STANDARD
-10: 10 ROWS
-1: LEAD (63% Sn/37% Pb)
-2: LEAD-FREE (96.5% Sn/3% Ag/.5% Cu)

D.SCHMELZ 01/08/2014 SHEET 1 OF 6
520 PARK EAST BLVD. NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
eMail info@SAMTEC.com code 55322

DESCRIPTION:
1.0mm PITCH ZRAY ASSEMBLY

F:DWG\MISC\MKTG\ZA1-XX-X-XX-X-XX-X-MKT.SLDDRW

**FIG 2**
ZA1-20-2-1.00-X-10 SHOWN
(DUAL COMPRESSION)
(DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)
(SOME CENTER FEATURES REMOVED FOR CLARITY)

**FIG 3**
ZA1-30-2-1.00-X-10 SHOWN
(DUAL COMPRESSION)
(DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)
(SOME CENTER FEATURES REMOVED FOR CLARITY)

**FIG 4**
ZA1-40-2-1.00-X-10 SHOWN
(DUAL COMPRESSION)
(DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)
(SOME CENTER FEATURES REMOVED FOR CLARITY)
FIG 5
ZA1-10-1-1.00-X-10-X SHOWN
(SINGLE COMPRESSION)
(DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)
(SOME CENTER FEATURES REMOVED FOR CLARITY)

TABLE 4

<table>
<thead>
<tr>
<th>No OF POS</th>
<th>&quot;D&quot;</th>
<th>&quot;E&quot;</th>
<th>&quot;F&quot;</th>
</tr>
</thead>
<tbody>
<tr>
<td>-20</td>
<td>21.40 [843]</td>
<td>19.00 [748]</td>
<td>19.00 [748]</td>
</tr>
</tbody>
</table>
FIG 7

ZA1-10-1-1.XX-X-X-X-X-X-X-X SHOWN
(SINGLE COMPRESSION WITH PPP)
(DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 6)
(SOME CENTER FEATURES REMOVED FOR CLARITY)

<table>
<thead>
<tr>
<th>No OF POS</th>
<th>&quot;H&quot;</th>
</tr>
</thead>
<tbody>
<tr>
<td>-10</td>
<td>2.20 [0.087]</td>
</tr>
<tr>
<td>-20</td>
<td>7.20 [0.283]</td>
</tr>
</tbody>
</table>